

SURFACE ACOUSTIC WAVE DEVICE

Abstract of the Disclosure

An object of the present invention is to provide a filter that enables to manufacture in a multi-chip package with ease and that is of small size and multi-function or multi-mode. In a constitution of the present invention, a filter comprises a package comprising a base on one main surface thereof a conductor is formed, and a plurality of surface acoustic wave chips comprising a plurality of interdigital transducers formed on one main surface of a piezoelectric substrate, signal terminals disposed on facing sides on the piezoelectric substrate, and ground terminals disposed on the piezoelectric substrate. Here, the plurality of surface acoustic wave chips, at the signal terminals and the ground terminals, is bonded to the conductor in a face down way.

Figure 4

This Sheet Has Been Replaced

